Creating Firmware Update Image for KW45B41Z/K32W148 using Over the Air Programming Tool

Rev. 1 — 21 March 2023

**Application note** 

#### **Document information**

Information	Content
Keywords	AN13860, OTAP, KW45B41Z, Firmware Update Images
Abstract	This application note describes the steps to create and upgrade the image on the KW45/K32W1 Evaluation Kit board



## 1 Introduction

This document provides the steps to create and upgrade the image on the KW45/K32W1 Evaluation Kit (EVK) board.

The demo can be run using two applications:

- OTAP Client-embedded application
- · Over the Air Programming PC application

The OTAP Client-embedded application has two versions: ATT version and L2CAP version. Each version uses a different transfer method.

The OTAP Client is a GAP peripheral which advertises the Bluetooth Low Energy (Bluetooth LE) OTAP service and waits for a connection from an OTAP server. After an OTAP server connects, the OTAP Client waits for it to write the OTAP control point CCCD, and then starts sending commands via ATT indications.

The demo applications use external storage by default. The internal storage is viable only if there is enough space in the internal flash for the upgrade image. The flash in this case must be at least twice the size of the largest application.

## 2 **Prerequisites**

To create an image to upgrade, the following prerequisites are required:

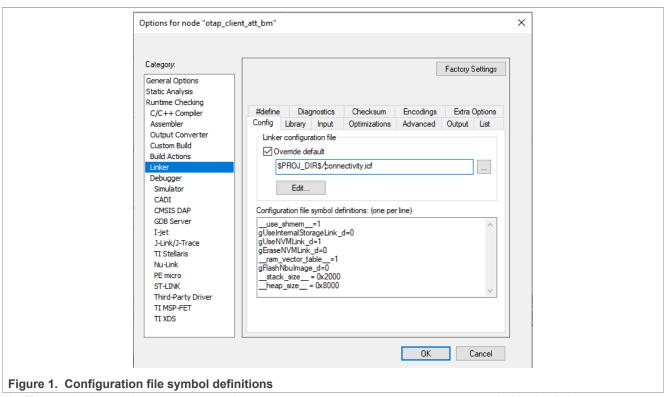
- MCUXpresso IDE v11.6.0 or later or IAR EW for Arm, can be downloaded from MCUXpresso-IDE
- Over the Air Programming tool 1.0.4.1 or above, can be downloaded from Over the Air Programming
- KW45B41Z/K32W148 board
- A smartphone with IoT toolbox NXP app, available for Android and iOS

### 3 Software setup with IAR

To configure the software, follow the steps below:

- 1. To use the external storage, you must do some changes. Several configuration options must be set up in both the source files and the linker options of the toolchain:
  - a. On the app\_preinclude.h, make sure that gAppOtaExternalStorage\_c is set to "1".
  - b. The OTAP demo applications for IAR EW IDE have some setting in the linker options as shown in Figure 1.

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2. To use the internal storage, set up the gUseInternalStorageLink\_d=1 symbol in the linker configuration and set the gAppOtaExternalStorage\_value to "0".

#### Note:

The gEraseNVMLink\_d=1 IAR linker flag places some dummy bytes into the NVM region to invalidate the data and force the application to erase the entire NVM region. When generating an image for the OTA upgrade, this flag should be set to "0", as well as the gUseNvmLink\_d flag. Therefore, resulting in a smaller image size being transferred and lower power consumption. If the NVM region must be erased after the upgrade process, the erase sector bitmap must be used to mark the NVM sectors as erasable.

#### 3.1 OTAP image format file

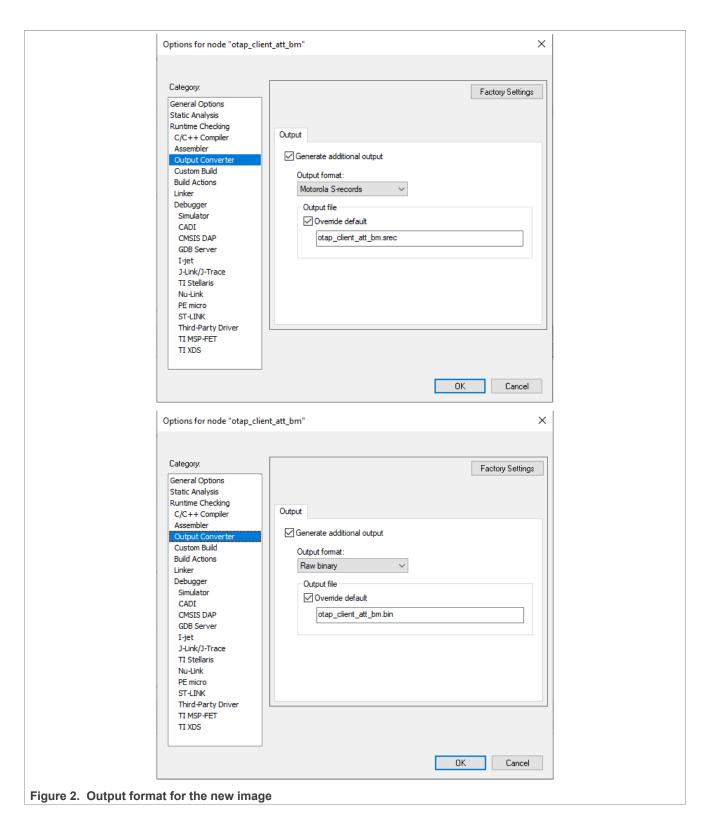
The Bluetooth LE OTAP image file has a binary file format. It is composed of a header followed by a number of subelements. The header describes general information about the file. There are some predefined subelements of a file but an end manufacturer may add manufacturer-specific subelements. The header does not have details of the subelements. The type of each piece is described.

To enable the creation of a SREC and BIN file for your embedded application in IAR Embedded Workbench, the steps are described as follows:

- 1. Open the target properties.
- 2. Go to the Output Converter tab.
- 3. Activate the Generate additional output checkbox.
- 4. Select the Motorola or Raw Binary option from the Output format drop-down menu.

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## 4 Software setup with MCUXpresso

To create the image for the application, you must deploy the **Binaries** icon in the workspace. Click the right mouse button on the .axf file and select **Binary Utilities** > **Create S-Record**. The S-Record file is saved at the Debug folder in the workspace with .srec extension.

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Figure 2. Pinery Utilities to create the new in	<u>-</u>	<u>-</u> · ··	

Figure 3. Binary Utilities to create the new image

A Motorola S-record (SREC) file is an ASCII format file which contains binary information. Common file extensions are .srec, .s19, .s28, .s37 and others. Most modern compiler toolchains can generate an SREC format executable. In MCUXpresso IDE, go to **Project properties** > **Settings** > **Build steps** window and press the **Edit** button for the Post-build steps. A **Post-build steps** window shows up in which the following command must be added:

```
arm-none-eabi-objcopy -v -0 srec --only-section=.text --only-section=.data --
only-section=.ARM.exidx
"${BuildArtifactFileName}"
"${BuildArtifactFileBaseName}.srec"
```

A snapshot of this window is shown in Figure 4.

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## 5 How to create an image with OTAP tool

This section provides the steps required to create an image for the KW45B41Z-EVK:

1. Navigate to Over the Air Programming tool.

	<u> </u>	0						
	Vver The Air Programming				· · ·	- C	×	:
	Select OTA Protocol:	💾 Browse File	🖾 Clear File	Save Fil	e as Binary	₩, <sup>%</sup> %(	¢ 1	ļ
	STAP Bluetooth LE • 🐨		(	Drag & drop .k	pin/.srec files here			
	Select Server Port:							
	🜵 No Serial Ports Detected 🔯	OTA Header     Upgrade File Identifier:	OxB1EF11E	^	OTA Transfer Details			
	Select Baud Rate:	Header Version:	0x0100					
	115200	Header Length: Header Field Control:	0x0 0x0000					
	Filter Binaries by Processor Type:	Manufacturer Code: Image Type:	0x01FF 0x0001					
	NONE -	Image Version: Stack Version:	0x0111111141000005 0x0002					
	✓ Filter:	Header String:	NXP BLE OTAP Demo Ima	9				
		Total Image Size: Security Credential Version:	0x0 0x01	Include				
		Upgrade File Destination:	OxFFFF	Include				
		HW Version Minimum HW Version:	0x1					
		Maximum HW Version:	0x2028	✓ Include	Save Session Log	Clear Log		
			onnect to OTAP Serv	er	Start OTAP	Cancel Tr		_
		Selected Processor: NONE					Х	х
Figure 5 Over the Air	Programming tool							

- 2. Drag and drop your .s19 /.srec /.bin.
- 3. To process the binary, select **KW45**.

🕌 Processor Selecti	on		_	
	firmware file has been sel ent board processor and a		vailable:	
<ul> <li>KW45</li> <li>QN9090/K32V</li> </ul>	C KW36/KW38	○ KW41Z	O QN9080	
Selected Processor:				
Contains bootlo	ader			
✓ Preserve NVM				
Store OTAP file of	on server.			
			ОК	Cancel

#### Figure 6. Processor selection for the KW45

4. You can now select the type of image you want to upgrade. The type can either be the application (M33) or the KW45 radio (M3), or both.

M33 settings									
Selected file:	kw45b41zevk_wireless_uart_bm.sree	:							
Will update:	KW45Z (MCU)	KW45Z (MCU) ~							
Start address:	0x0000000		lmage size:	217628 bytes					
M3 settings									
Selected file:	Drag &	drop files here		Clear	Browse				
Will update:	KW45B (radio)								
Start address:	0x48800000		Image size:	0 bytes					
-									
<ul> <li>External Flash Settings</li> <li>Use External Flash</li> <li>Make sure that the "O</li> </ul>	TA Client'' application is also configured to p	place the OTA storage in the IN	NTERNAL flas	n I					
				ОК	Cancel				

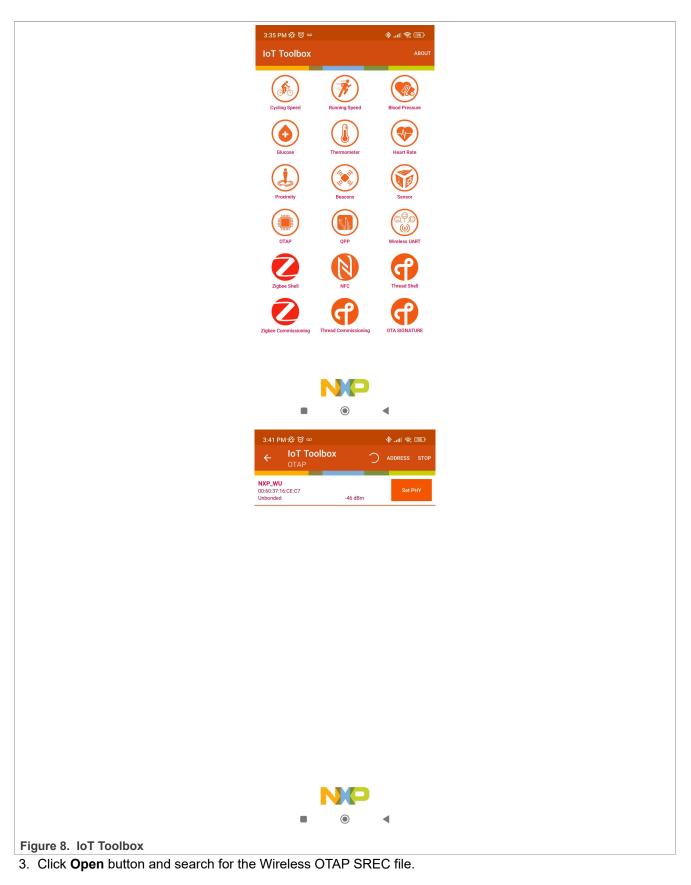
#### Figure 7. Image information for the KW45

5. Save this file in a known location.

## 6 Testing the OTAP software

To test the OTAP software, steps are as follows:

- 1. Open the IoT Toolbox app and select the OTAP demo.
- 2. To start scanning for a suitable advertiser, click SCAN.



4. To start the transfer, click Upload. Wait until the confirmation message is displayed.

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← IoT To OTAP	ol <sub>Disco</sub>	ONNECT	SET PHY	READ PHY
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File Name		FSL BLE	OTAP Demo	Image File
File Version			0x01111111	41000005
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5. Wait a few seconds until the OTAP bootloader has finished programming the new image. The wireless UART application starts automatically, with the RGB LED blinking.

## 7 Revision history

The <u>Table 1</u> lists the substantive changes done to this document since the initial release.

Revision number	Date	Substantive changes
1		<ul> <li>Updated the download link for the otap tool in <u>Section 2</u></li> <li>Updated the title to "Creating Firmware Update Image for KW45B41Z/K32 W148 using Over the Air Programming Tool"</li> </ul>
0	10 February 2023	Initial release

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